

NewJRC Announces Shipment of ICs Produced Collaboratively with UMCJ

Tokyo, Japan, August 2, 2011 – New Japan Radio Co., Ltd. (NewJRC; TSE:6911) today announced the shipment of ICs produced through a manufacturing partnership with semiconductor foundry UMC JAPAN (UMCJ). The two companies completed joint development of processes on which ICs were manufactured collaboratively, achieved readiness of production systems, and began shipments of these ICs based on a partnership agreement with details as follows:

1) Process Development

The two companies focused on 50V BCD and 35V CMOS processes. Ported from NewJRC, the 50V BCD (bipolar, CMOS, double diffused MOS) process leverages NewJRC's strengths in bipolar and DMOS (double diffused MOS) for N-channel and P-channel power devices and integrates its core BCD process with UMCJ's 0.35um CMOS (Complementary Metal Oxide Semiconductor) technology for 200mm wafer production. The maximum 5-layer interconnect structure with a 3-micron thick film-metal for the top layer is achieved using UMCJ's planarizing technology. The 35V CMOS process offers a high voltage solution with the same UMCJ 0.35um CMOS technology.

2) Product Development

① 50V BCD process products

These products are mainly on a switching regulator and a series regulator, with delivery beginning from June 2011. Development of the LED driver and the motor driver is continuing with plans for future market launch. The use of 50V BCD technologies widens the input voltage range of power supply ICs and motor ICs and thus stimulates business expansion. The plan is to release 15 products by the first half of fiscal year 2011 and 30 products in total by the end of fiscal year 2011.

② 35V CMOS process products

These products are mainly on the audio line amplifier, with delivery beginning from August 2010. Development of the LCD driver and an electronic volume for the audio is continuing with plans for future market launch. The plan is to release 15 total products by the end of fiscal year 2011.

3) Production System

The 200mm wafer production line is housed in SAGA ELECTRONICS Co., LTD., NewJRC's subsidiary, and serves as the primary semiconductor assembly factory for greater manufacturing efficiency. Various production facilities were newly established and reinforced to extend production capabilities through wafer testing and assembly.

For quality improvement and production stability, device variation data from UMCJ's Tateyama fab and wafer reliability data from SAGA ELECTRONICS Co., LTD., were collected and managed through a system built by Kawagoe Works.

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